CLAIMS

What is claimed is:

1	1. A computer assembly comprising:		
2	a chassis;		
3	a mounting module rigidly coupled to the chassis, the mounting module		
4	for cooling the computer assembly; and		
5	at least one circuit board suspended from the module, wherein the at least		
6	one circuit board having a known orientation relative to the module and at least one		
7	circuit board having a variable orientation relative to the chassis.		
1	2. The computer assembly of claim 1 which includes a stabilization support		
2	mechanism for ensuring that the at least one circuit board remains in the known		
3	orientation relative to the module.		
1	The computer assembly of claim 1 wherein the mounting module		
2	comprises:		
3	a heatsink; and		
4	a daughter board coupled to the heatsink, wherein the daughter board		
5	includes a processor.		
1	4. The computer assembly of claim 3 wherein the processor is in contact wit		
2	the at least one circuit board.		
1	5. The computer assembly of claim 3 wherein the daughter board is coupled		
2	to the heatsink via a spring-loaded mount.		

1	6.	The computer assembly of claim 5 wherein the printed circuit board is	
2	mounted to the chassis via a plurality of standoffs and fasteners at its periphery.		
1	7.	The computer assembly of claim 6 wherein the fasteners of the printed	
2	circuit expand longitudinally within apertures in the daughter board to secure the circuit		
3	board to the h	neatsink assembly.	
1	8.	The computer assembly of claim 7 wherein the heatsink assembly is	
2	located relative to the at least one printed circuit board via pin features.		
1	9.	A mounting module for a computer assembly comprising:	
2		a heatsink assembly for cooling the computer assembly, wherein the	
3	heatsink assembly is coupled rigidly to a chassis of the computer assembly and is also		
4	coupled to a printed circuit board within the computer assembly, wherein the printed		
5	circuit board has a known orientation relative to the module and has a variable orientation		
6	relative to the chassis.		
1	10.	The mounting module of claim 9 which includes a stabilization support	
2	mechanism for ensuring that the at least one circuit board remains in the known		
3	orientation relative to the module.		
1	11.	The mounting module of claim 9 wherein the heatsink assembly	
2	comprises:		
3	٠	a heatsink; and	
4		a daughter board coupled to the heatsink, wherein the daughter board	

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6

includes a processor.

- 1 12. The mounting module of claim 11 wherein the processor is in contact with 2 the at least one circuit board.
- 1 13. The mounting module of claim 11 wherein the daughter board is coupled to the heatsink via a spring-loaded mount.